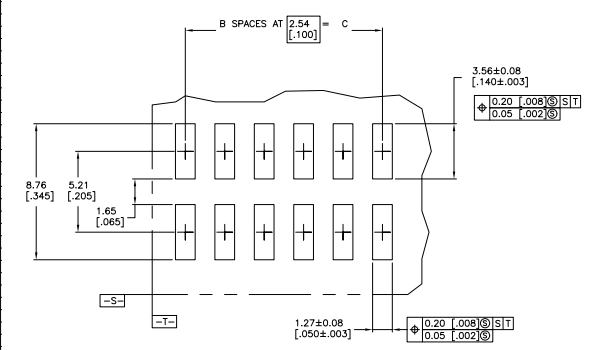
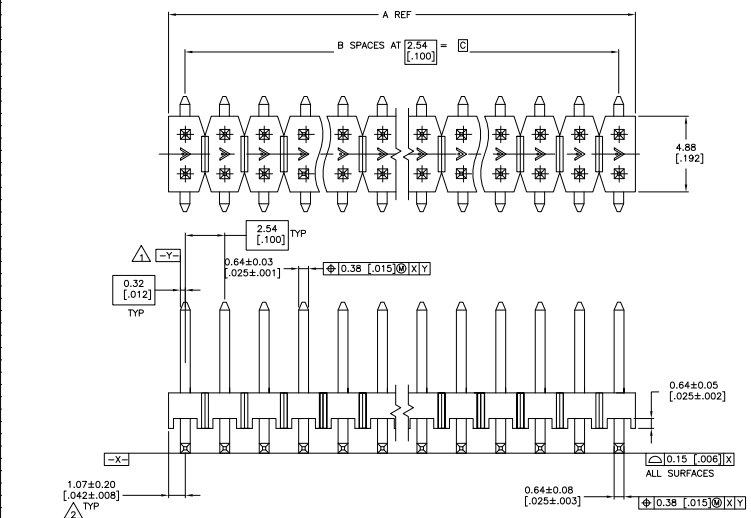
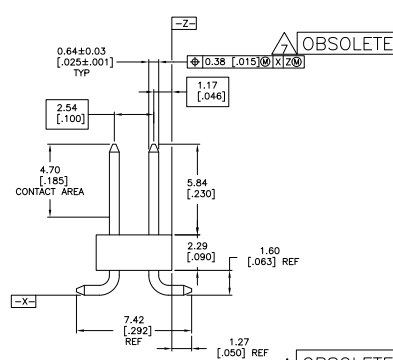


REV	DATE	DESCRIPTION	BY	CHK	APP
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K2		REVISED PER EDD-11-004587			



RECOMMENDED PCB LAYOUT
 FOR USE WITH .008 THICK STENCIL

- △ THE NOTED DIMENSIONS APPLY AT THE INTERSECTION OF THE POST AND THE HOUSING.
- △ THE NOTED DIMENSION APPLIES FROM THE BASIC DIMENSION (NOT THE POST CENTERLINE) TO THE SURFACE INDICATED.
- △ 0.000762[0.00030] GOLD ON CONTACT AREA, 0.00254-0.00508[0.00100-0.00200] MATTE TIN-LEAD ON SOLDER TAIL, ALL OVER 0.00127[0.00050] NICKEL.
- △ HOUSING: LCP, COLOR-BLACK. POSTS: PHOSPHOR BRONZE.
- △ 0.000762[0.00030] GOLD ON CONTACT AREA, 0.00254-0.00508[0.00100-0.00200] MATTE TIN ON SOLDER TAIL, ALL OVER 0.00127[0.00050] NICKEL.
- △ PRELIMINARY PART - NOT RELEASED FOR PRODUCTION.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINIS



REV	DATE	DESCRIPTION	BY	CHK	APP
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△ SUPERSEDED BY 6-146130-0

THIS DRAWING IS A CONTROLLED DOCUMENT. DATE: 03-28-14

TE Connectivity

SURFACE MOUNT HEADER ASSEMBLY, MOD II, BREAKAWAY, VERTICAL, DOUBLE ROW, 100 X 100 CL, 025 SQ POST

DATE: 03-28-14

REV: 1

REVISED TO: 146130-1

CUSTOMER DRAWING